

Version with markings to show changes made

IN THE CLAIMS:

18. (Twice Amended) An apparatus for dispensing flux on a substrate having a plurality of conductive terminals thereon, the apparatus comprising:

a data processing device adapted for [determining an optimum] controlling valve pressure, flux viscosity, and flux spray pattern based on a configuration of the substrate and an arrangement pattern of conductive terminals thereon; and

a flux dispense nozzle configured for spraying flux [at a valve pressure range between about 1.5 psi and about 30 psi to deposit the flux] on the [plurality of] conductive terminals, wherein

the data processing device controls the flux viscosity in a range between about 10 centipoises and about 150 centipoises and controls the valve pressure for spraying the flux in a range between about 1.5 psi and about 30 psi [movement of the flux dispense nozzle in at least two dimensions relative to the substrate].

22. (Twice Amended) The apparatus of claim 18, wherein the data processing device controls movement of the flux dispense nozzle in at least two dimensions relative to the substrate and decides a plurality of subsets based on the configuration of the substrate and the arrangement pattern of conductive terminals thereon, each subset comprising a plurality of conductive terminals closely located to each other.